IPC ASSOCIATION CONNECTED ELECTRONICS INDUSTRI	Material Composi © Copyright 2005. IPC, international and Pan-Ar	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					fg Informati	ion	
upplier Infor								,					
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2023-06-08			
Contact Name		Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Ste	wards	Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
uthorized Repre	esentative*	Title - Repre	Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Ste	wards	Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Reque	Requester Item Number Mfr I		em Number Mfr Item Name			Effective Date	Version	Version Manufacturing Site		V	Weight*	UOM	Unit Type
		MC100LVEL30DWR 2G	LVEL30DWR BBG ECL FLIP FLOP TRPL			2023-06-08		7	TW2		517.71	mg	Each
Ianufacturin	g Proccess Information	n											
Termin	al Plating / Grid Array Materi	ial Terminal Base	Ferminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature Max Time at Pea		re Max Time at Peak	Temperat	ure Numb	per of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU Alloy	CU Alloy 3			260	) C		30	secon	ds 3		
omments													
TTENTION: M	SL 3 Rated item requires Ba	ake and Dry Pack (afte	r electrical test)			<u> </u>			·			·	·
or more informa	ation regarding material con	nposition please refer to	page 3						·				·

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and corner to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.33	mg	Supplier	Silicon (Si)	7440-21-3		9.33	mg
Die Attach	20.68	mg	Supplier	Silver (Ag)	7440-22-4		15.51	mg
			Supplier	Epoxy resins	129915-35-1		5.17	mg
Lead Frame	323.98	mg	Supplier	Silver (Ag)	7440-22-4		3.2398	mg
			Supplier	Zinc (Zn)	7440-66-6		0.648	mg
			Supplier	Iron (Fe)	7439-89-6		8.4235	mg
			Supplier	Copper (Cu)	7440-50-8		311.6688	mg
Mold Compound-Black	158.46	mg		Epoxy Phenol Resin	proprietary data		16.6383	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		141.8217	mg
Plating	4.79	mg	Supplier	Tin (Sn)	7440-31-5		4.79	mg
Wire Bond - Au	0.47	mg	Supplier	Gold (Au)	7440-57-5		0.47	mg